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PHIXEL WIF

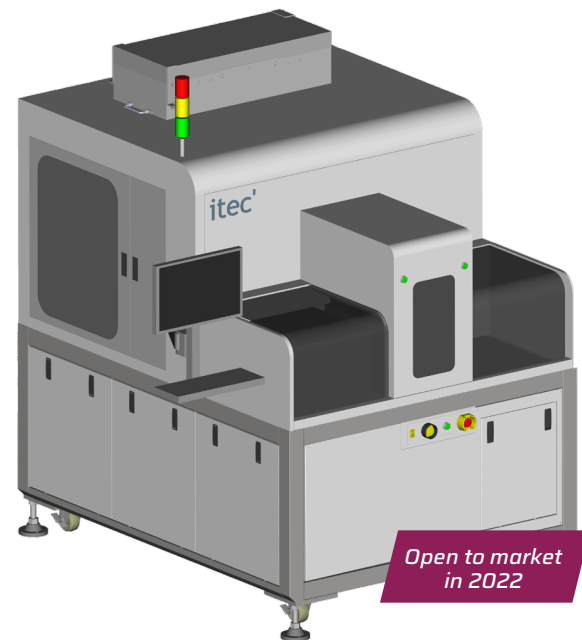
Wafer Inspection Film frame Carrier

Application

- Inspection after wafer dicing to detect surface defects
- Inspection after package singulation to detect package, mark, lead and plating defects

Key Feature

- 2D surface inspection, stationary camera
- 128-Thread processor
- 16K line scan camera resolution
- Support high density wafer up to >500K dies
- FOV 50mm, 3.4 μm pixel resolution or 0.85 μm by upscaled image
- Auto 2D barcode reading
- Vision performance comparable to high-end AOI
- High throughput at high-volume manufacturing rate
- Granit base inspection work holder
- Support 6", 8" 12" wafer on Frame Film Carrier
- Automatic wafer map match
- Two cassettes at input loader
- SEMI standard with SECS/GEM interface



*Open to market
in 2022*

Post Dicing Wafer AOI

Imaging System

Camera	16K line scan monochrome
Number of camera	1
Resolution / FOV	3.1 μm , FOV: 52mm
Min object detection	10 μm
Lighting	Blue coaxial

Inspection Categories

Program Mode:	Fast programming for common reject criteria
Reject treatment:	Electronic map
Inspection View:	Top view
Inspection items:	Chip defects: <ul style="list-style-type: none">- Chipping- Damaged bump large than percentage of bump area- Bump diameter- Shorted umps contact- Missing bump- Scratch- Probe mark size large than percentage of bump area- Cracked die- Cutting Kerf shift- Discoloration

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